DATA SHEET

74LV126
Quad buffer/line driver (3-State)

Product specification
Supersedes data of 1997 Feb 03
IC24 Data Handbook

1998 Apr 28

Philips
Semiconductors

PHILIPS

Quad buffer/line driver (3-State) 74LV126

FEATURES

- Wide operating voltage: 1.0 to 5.5 V
- Optimized for low voltage applications: 1.0 to 3.6 V
- Accepts TTL input levels between V_{CC} = 2.7 V and V_{CC} = 3.6 V
- Typical V_{OLP} (output ground bounce) < 0.8 V at V_{CC} = 3.3 V, T_{amb} = 25°C
- Typical V_{OHV} (output V_{OH} undershoot) > 2 V at V_{CC} = 3.3 V, T_{amb} = 25°C
- Output capability: bus driver
- I_{CC} category: MSI

DESCRIPTION

The 74LV126 is a low-voltage Si-gate CMOS device that is pin and function compatible with 74HC/HCT126.

The 74LV126 consists of four non-inverting buffers/line drivers with 3-state outputs. The 3-state outputs (nY) are controlled by the output enable input (nOE). A LOW at nOE causes the outputs to assume a high impedance OFF-state.

QUICK REFERENCE DATA

GND = 0 V; T_{amb} = 25°C; $t_r = t_f \leq 2.5$ ns

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
t_{PHL}/t_{PLH}	Propagation delay nA to nY	C_L = 15 pF; V_{CC} = 3.3 V	9	ns
C_I	Input capacitance		3.5	pF
C_{PD}	Power dissipation capacitance per buffer	V_{CC} = 3.3 V; V_I = GND to V_{CC}[1]	23	pF

NOTE:

1. C_{PD} is used to determine the dynamic power dissipation (P_D in µW)
   $P_D = C_{PD} \times V_{CC}^2 \times f_i + \sum (C_L \times V_{CC}^2 \times f_o)$ where:
   f_i = input frequency in MHz; C_L = output load capacitance in pF;
   f_o = output frequency in MHz; V_{CC} = supply voltage in V;
   $\sum (C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs.

ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	PKG. DWG. #
14-Pin Plastic DIL	–40°C to +125°C	74LV126 N	74LV126 N	SOT27-1
14-Pin Plastic SO	–40°C to +125°C	74LV126 D	74LV126 D	SOT108-1
14-Pin Plastic SSOP Type II	–40°C to +125°C	74LV126 DB	74LV126 DB	SOT337-1
14-Pin Plastic TSSOP Type I	–40°C to +125°C	74LV126 PW	74LV126PW DH	SOT402-1

PIN DESCRIPTION

PIN NUMBER	SYMBOL	FUNCTION
1, 4, 10, 13	1OE – 4OE	Output enable inputs (active HIGH)
2, 5, 9, 12	1A – 4A	Data inputs
3, 6, 8, 11	1Y – 4Y	Data outputs
7	GND	Ground (0 V)
14	V_{CC}	Positive supply voltage

FUNCTION TABLE

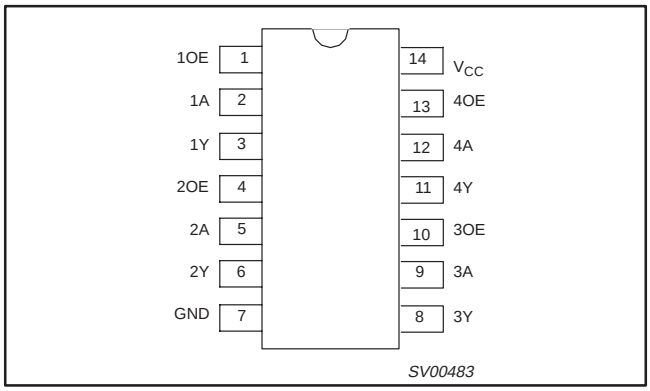
INPUTS		OUTPUTS
nOE	nA	nY
H	L	L
H	H	H
L	X	Z

NOTES:

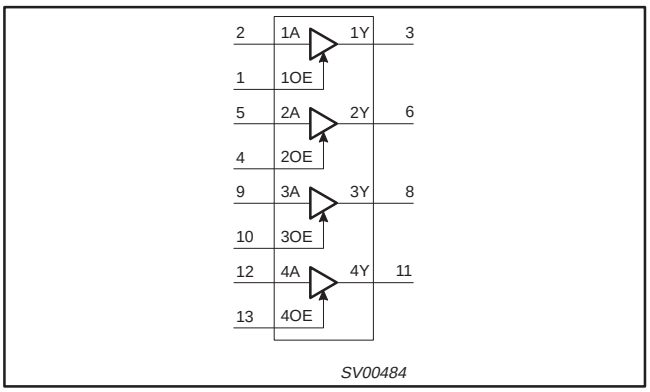
H = HIGH voltage level
L = LOW voltage level
X = don't care
Z = high impedance OFF-state

Quad buffer/line driver (3-State) 74LV126

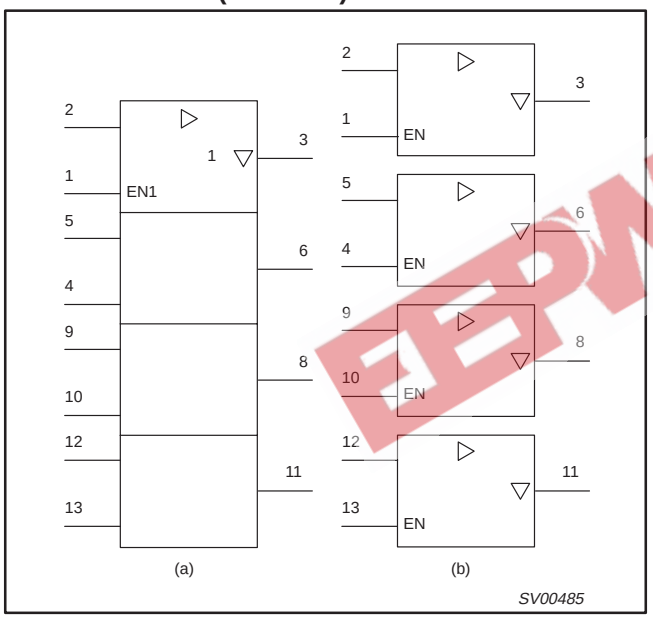
PIN CONFIGURATION



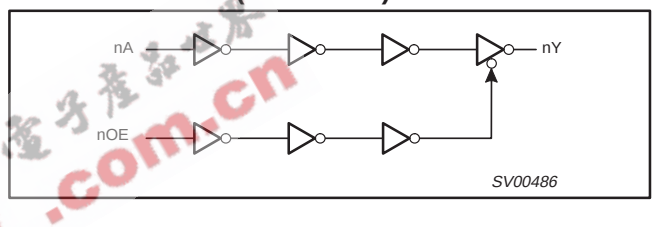
LOGIC SYMBOL



LOGIC SYMBOL (IEEE/IEC)



LOGIC DIAGRAM (ONE GATE)



RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
V_{CC}	DC supply voltage	See Note 1	1.0	3.3	5.5	V
V_I	Input voltage		0	–	V_{CC}	V
V_O	Output voltage		0	–	V_{CC}	V
T_{amb}	Operating ambient temperature range in free air	See DC and AC characteristics	–40 –40		+85 +125	°C
t_r, t_f	Input rise and fall times	V_{CC} = 1.0V to 2.0V V_{CC} = 2.0V to 2.7V V_{CC} = 2.7V to 3.6V V_{CC} = 3.6V to 5.5V	– – – –	– – – –	500 200 100 50	ns/V

NOTE:
1. The LV is guaranteed to function down to V_{CC} = 1.0V (input levels GND or V_{CC}); DC characteristics are guaranteed from V_{CC} = 1.2V to V_{CC} = 5.5V.

ABSOLUTE MAXIMUM RATINGS[1, 2]

In accordance with the Absolute Maximum Rating System (IEC 134).
Voltages are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V_{CC}	DC supply voltage		–0.5 to +7.0	V
$\pm I_{IK}$	DC input diode current	$V_I < –0.5$ or $V_I > V_{CC} + 0.5V$	20	mA
$\pm I_{OK}$	DC output diode current	$V_O < –0.5$ or $V_O > V_{CC} + 0.5V$	50	mA
$\pm I_O$	DC output source or sink current – bus driver outputs	$–0.5V < V_O < V_{CC} + 0.5V$	35	mA
$\pm I_{GND}$, $\pm I_{CC}$	DC V_{CC} or GND current for types with – bus driver outputs		70	mA
T_{stg}	Storage temperature range		–65 to +150	°C
P_{TOT}	Power dissipation per package – plastic DIL – plastic mini-pack (SO) – plastic shrink mini-pack (SSOP and TSSOP)	for temperature range: –40 to +125°C above +70°C derate linearly with 12 mW/K above +70°C derate linearly with 8 mW/K above +60°C derate linearly with 5.5 mW/K	 750 500 400	mW

NOTES:
1. Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
2. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

DC ELECTRICAL CHARACTERISTICS

Over recommended operating conditions, voltages are referenced to GND (ground = 0 V)

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS					UNIT
			-40°C to +85°C			-40°C to +125°C		
			MIN	TYP[1]	MAX	MIN	MAX	
V_{IH}	HIGH level Input voltage	V_{CC} = 1.2 V	0.9			0.9		V
		V_{CC} = 2.0 V	1.4			1.4		
		V_{CC} = 2.7 to 3.6 V	2.0			2.0		
		V_{CC} = 4.5 to 5.5 V	0.7 * V_{CC}			0.7 * V_{CC}		
V_{IL}	LOW level Input voltage	V_{CC} = 1.2 V			0.3		0.3	V
		V_{CC} = 2.0 V			0.6		0.6	
		V_{CC} = 2.7 to 3.6 V			0.8		0.8	
		V_{CC} = 4.5 to 5.5			0.3 * V_{CC}		0.3 * V_{CC}	
V_{OH}	HIGH level output voltage; all outputs	V_{CC} = 1.2 V; $V_I = V_{IH}$ or V_{IL}; $–I_O$ = 100µA		1.2				V
		V_{CC} = 2.0 V; $V_I = V_{IH}$ or V_{IL}; $–I_O$ = 100µA	1.8	2.0		1.8		
		V_{CC} = 2.7 V; $V_I = V_{IH}$ or V_{IL}; $–I_O$ = 100µA	2.5	2.7		2.5		
		V_{CC} = 3.0 V; $V_I = V_{IH}$ or V_{IL}; $–I_O$ = 100µA	2.8	3.0		2.8		
		V_{CC} = 4.5 V; $V_I = V_{IH}$ or V_{IL}; $–I_O$ = 100µA	4.3	4.5		4.3		
V_{OH}	HIGH level output voltage; BUS driver outputs	V_{CC} = 3.0 V; $V_I = V_{IH}$ or V_{IL}; $–I_O$ = 8mA	2.40	2.82		2.20		V
		V_{CC} = 4.5 V; $V_I = V_{IH}$ or V_{IL}; $–I_O$ = 16mA	3.60	4.20		3.50		
V_{OL}	LOW level output voltage; all outputs	V_{CC} = 1.2 V; $V_I = V_{IH}$ or V_{IL}; I_O = 100µA		0				V
		V_{CC} = 2.0 V; $V_I = V_{IH}$ or V_{IL}; I_O = 100µA		0	0.2		0.2	
		V_{CC} = 2.7 V; $V_I = V_{IH}$ or V_{IL}; I_O = 100µA		0	0.2		0.2	
		V_{CC} = 3.0 V; $V_I = V_{IH}$ or V_{IL}; I_O = 100µA		0	0.2		0.2	
		V_{CC} = 4.5 V; $V_I = V_{IH}$ or V_{IL}; I_O = 100µA		0	0.2		0.2	

DC ELECTRICAL CHARACTERISTICS (Continued)

Over recommended operating conditions, voltages are referenced to GND (ground = 0 V)

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS					UNIT
			-40°C to +85°C			-40°C to +125°C		
			MIN	TYP[1]	MAX	MIN	MAX	
V_{OL}	LOW level output voltage; BUS driver outputs	V_{CC} = 3.0 V; V_I = V_{IH} or V_{IL}; I_O = 8mA		0.20	0.40		0.50	V
		V_{CC} = 4.5 V; V_I = V_{IH} or V_{IL}; I_O = 16mA		0.35	0.55		0.65	
I_I	Input leakage current	V_{CC} = 5.5 V; V_I = V_{CC} or GND			1.0		1.0	µA
I_{OZ}	3-State output OFF-state current	V_{CC} = 5.5 V; V_I = V_{IH} or V_{IL}; V_O = V_{CC} or GND			5		10	µA
I_{CC}	Quiescent supply current; MSI	V_{CC} = 5.5 V; V_I = V_{CC} or GND; I_O = 0			20.0		160	µA
ΔI_{CC}	Additional quiescent supply current per input	V_{CC} = 2.7 V to 3.6 V; V_I = V_{CC} – 0.6 V			500		850	µA

NOTE:
1. All typical values are measured at T_{amb} = 25°C.

AC CHARACTERISTICS

GND = 0V; t_r = t_f ≤ 2.5ns; C_L = 50pF; R_L = 500Ω

SYMBOL	PARAMETER	WAVEFORM	CONDITION	LIMITS					UNIT
				–40 to +85 °C			–40 to +125 °C		
			V_{CC}(V)	MIN	TYP[1]	MAX	MIN	MAX	
t_{PHL}/t_{PLH}	Propagation delay nA to nY	Figures 1, 2	1.2		55				ns
			2.0		19	24		31	
			2.7		14	18		23	
			3.0 to 3.6		10[2]	14		18	
			4.5 to 5.5			12		15	
t_{PZH}/t_{PZL}	3-state output enable time nOE to nY	Figures 1, 2	1.2		75				ns
			2.0		26	31		39	
			2.7		19	23		29	
			3.0 to 3.6		14[2]	18		23	
			4.5 to 5.5			15		19	
t_{PHZ}/t_{PLZ}	3-state output disable time nOE to nY	Figures 1, 2	1.2		65				ns
			2.0		24	32		39	
			2.7		28	24		29	
			3.0 to 3.6		14[2]	20		24	
			4.5 to 5.5			17		21	

NOTES:
1. Unless otherwise stated, all typical values are measured at T_{amb} = 25°C
2. Typical values are measured at V_{CC} = 3.3 V.

AC WAVEFORMS

V_M = 1.5 V at $V_{CC} \geq$ 2.7 V and $\leq$ 3.6 V;
$V_M = 0.5 \times V_{CC}$ at V_{CC} < 2.7 V and $\geq$ 4.5 V;
V_{OL} and V_{OH} are the typical output voltage drop that occur with the output load.
$V_X = V_{OL} + 0.3$ V at $V_{CC} \geq$ 2.7 V and $\leq$ 3.6 V;
$V_X = V_{OL} + 0.1 \times V_{CC}$ at V_{CC} < 2.7 V and $\geq$ 4.5 V.
$V_Y = V_{OH} - 0.3$ V at $V_{CC} \geq$ 2.7 V and $\leq$ 3.6 V;
$V_Y = V_{OH} - 0.1 \times V_{CC}$ at V_{CC} < 2.7 V and $\geq$ 4.5 V.

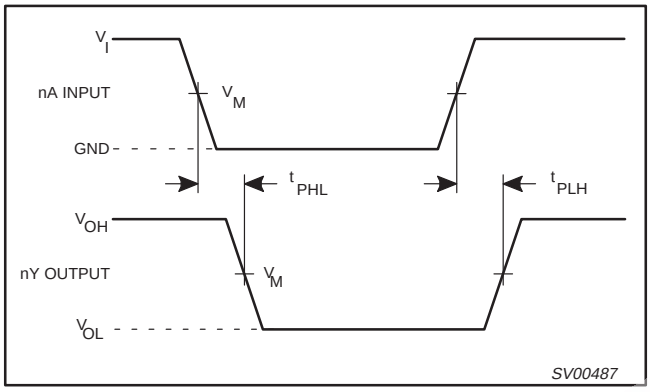


Figure 1. Input (nA, nB) to output (nY) propagation delays

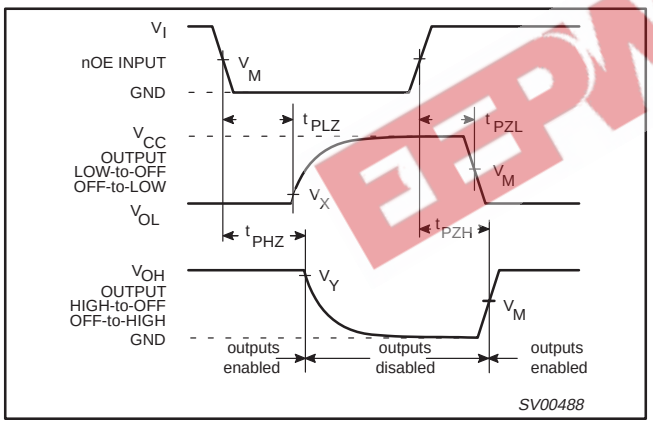


Figure 2. 3-state enable and disable times.

TEST CIRCUIT

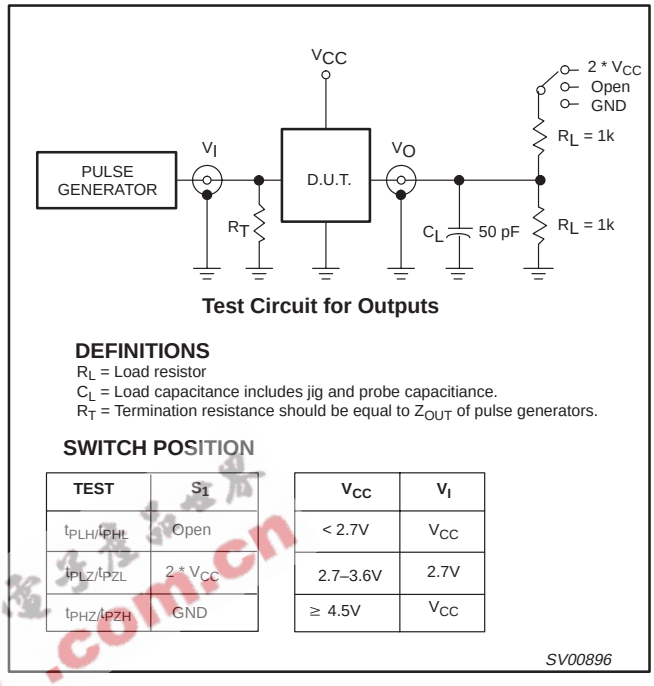
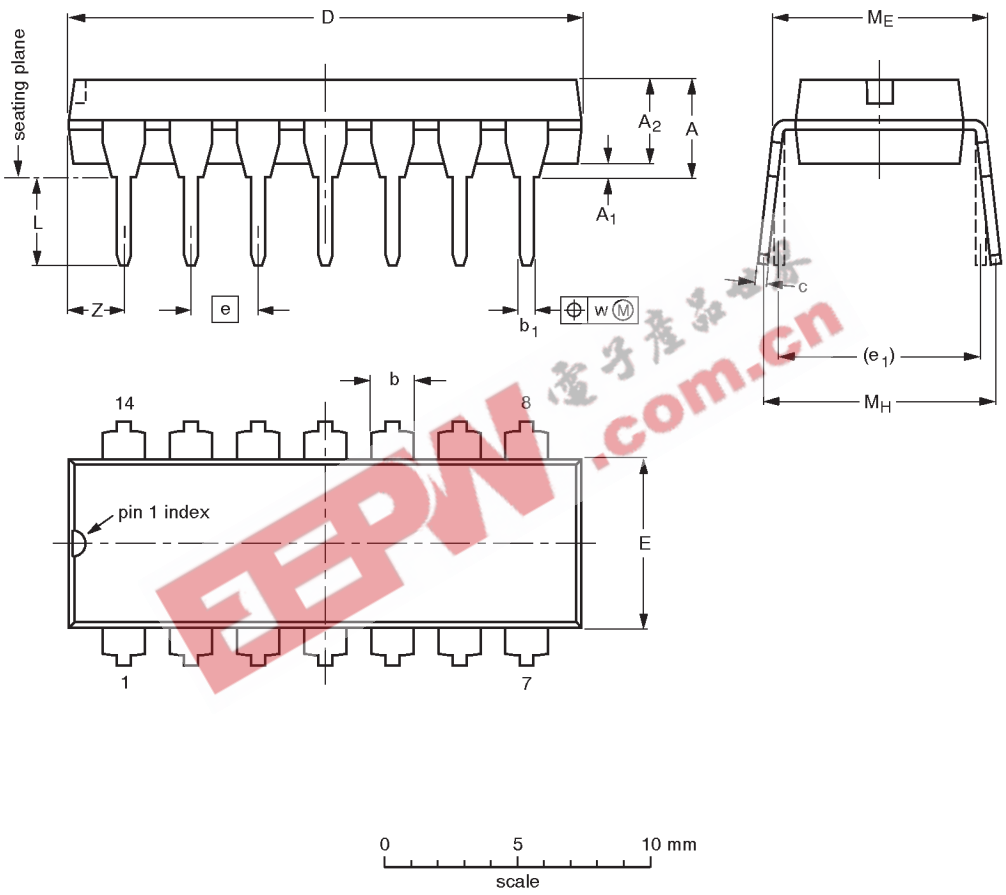


Figure 3. Load circuitry for switching times.

DIP14: plastic dual in-line package; 14 leads (300 mil) SOT27-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

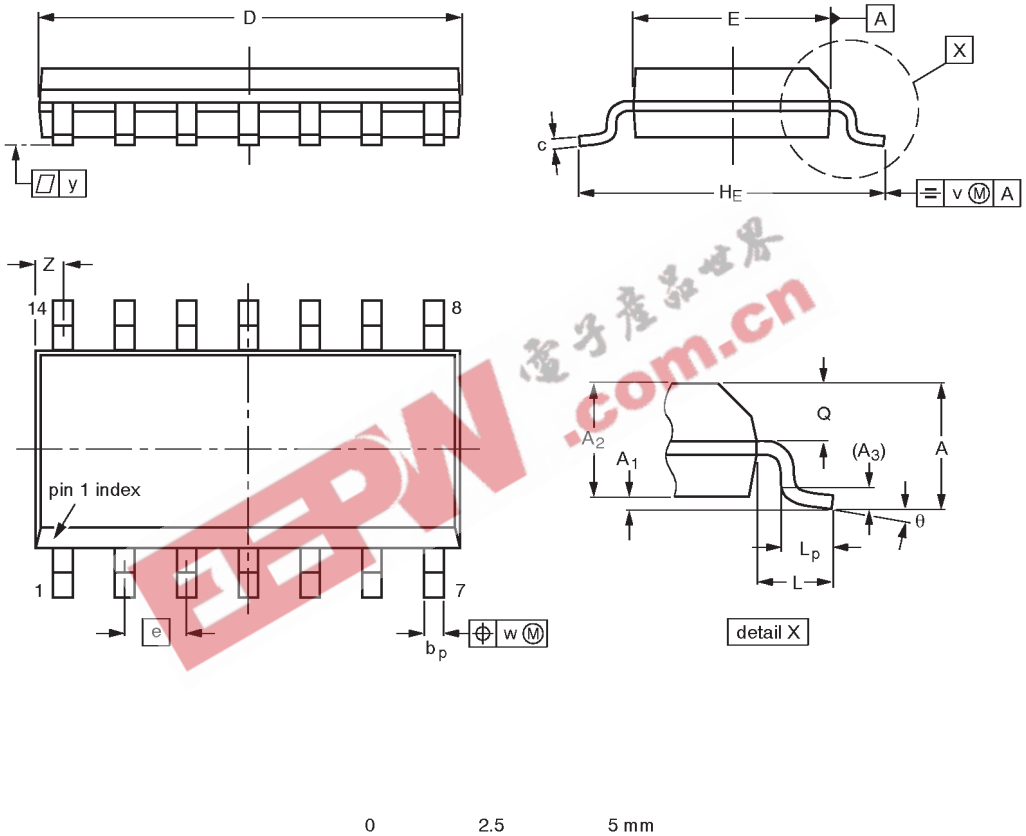
UNIT	A max.	A_1 min.	A_2 max.	b	b_1	c	D (1)	E (1)	e	e_1	L	M_E	M_H	w	Z (1) max.
mm	4.2	0.51	3.2	1.73 1.13	0.53 0.38	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.2
inches	0.17	0.020	0.13	0.068 0.044	0.021 0.015	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.087

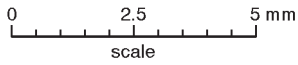
Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT27-1	050G04	MO-001AA				~~92-11-17~~ 95-03-11

SO14: plastic small outline package; 14 leads; body width 3.9 mm SOT108-1





DIMENSIONS (inch dimensions are derived from the original mm dimensions)

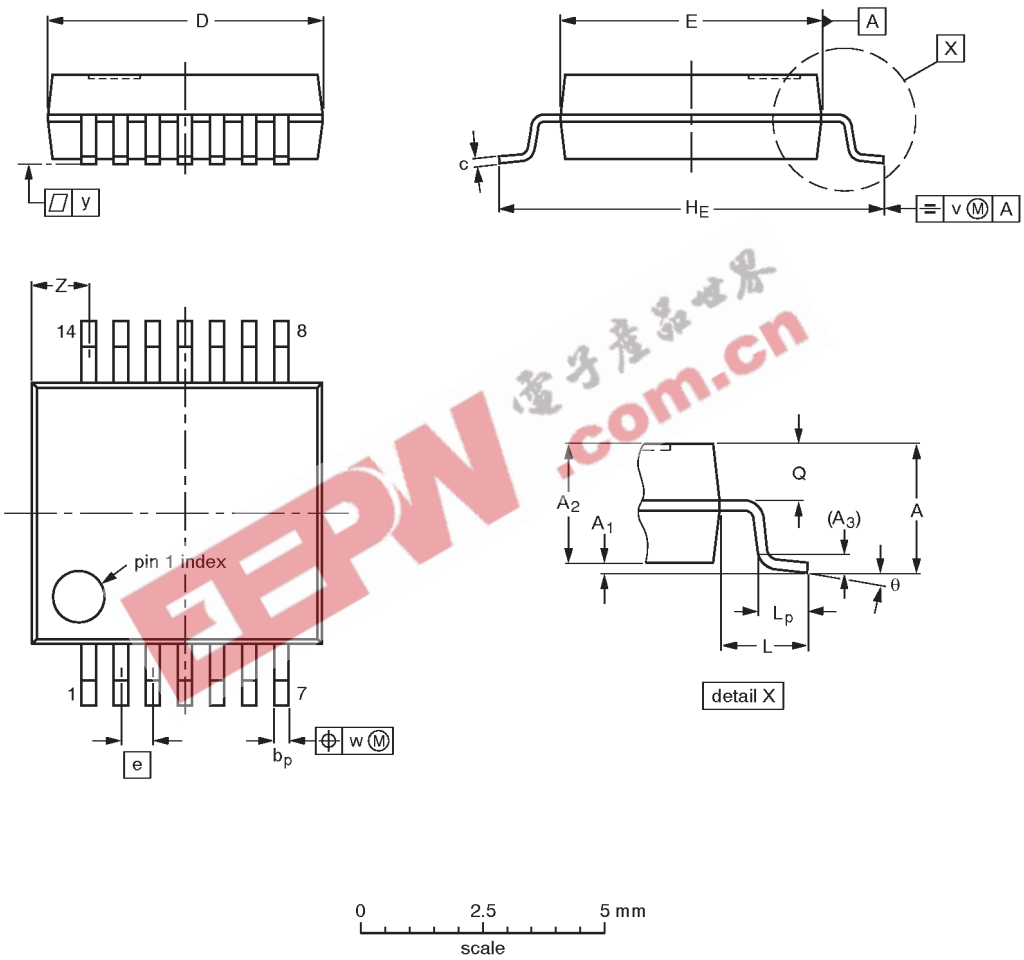
UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	8.75 8.55	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8° 0°
inches	0.069	0.0098 0.0039	0.057 0.049	0.01	0.019 0.014	0.0098 0.0075	0.35 0.34	0.16 0.15	0.050	0.24 0.23	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT108-1	076E06S	MS-012AB				~~91-08-13~~ 95-01-23

SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm **SOT337-1**



DIMENSIONS (mm are the original dimensions)

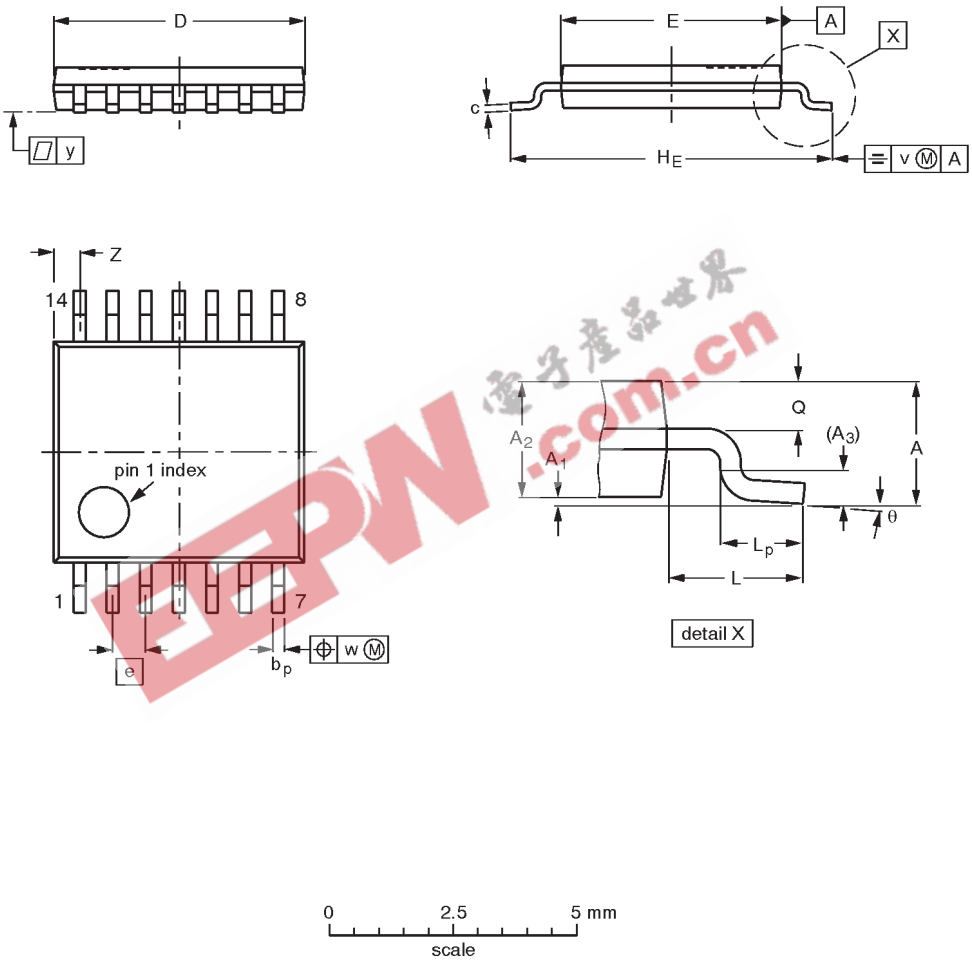
UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	6.4 6.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	1.4 0.9	8° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT337-1		MO-150AB				~~95-02-04~~ 96-01-18

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm **SOT402-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (2)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.72 0.38	8° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT402-1		MO-153				~~94-07-12~~ 95-04-04

NOTES

DEFINITIONS

Data Sheet Identification	Product Status	Definition
Objective Specification	Formative or in Design	This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.
Preliminary Specification	Preproduction Product	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.
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